L12	0	11 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 09:41
L14	181	5 and (deposit$5 near6 ((vapor adj deposition) or (cvd or pvd)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 10:56
L15	33	14 and ((wash$5 or clean$5) near7 (solder))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 09:55
L17	39	9 and (((vapor adj deposition) or (cvd or pvd)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 10:16
L18	1	8 and ((solder) near7 ((vapor adj deposition) or (cvd or pvd)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 11:23
L20	1	9 and ((solder) with ((vapor adj deposition) or (cvd or pvd)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 10:16
L21	42100	((metal or metallic) near3 (stencil or mask or template or resist))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 10:56
L22	57	21 and (solder$5 near6 ((vapor adj deposition) or (cvd or pvd)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 11:11
L23	12	22 and (((oxidation or oxide) or (clean$4 or wash$4)) near7 (solder))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 11:12
L24	· 130	(((((("0.5") near3 mil) or (("0.01" or "0.02") near2 (mm or millimeter)) or (("12" or "13") near2 (micron or "um"))) near5 (thick or thickness or height)) with (solder))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 11:23
L25	3	24 and ((solder) near7 ((vapor adj deposition) or (cvd or pvd)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 11:24

L26	2	("4,772,935").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/05 11:24
L27	57	"228"/$.ccls. and (solder with (protect$3 with time))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 12:03
L28	57	"228"/$.ccls. and (solder with (protect$4 with time))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 12:08
L29	22	"228"/$.ccls. and (solder with (nitrogen) with (clean$4 or wash$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 12:03
L30	10	"228"/$.ccls. and (solder with (protect$4 with (storage or transportation)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 12:13
L31	3	"29"/$.ccls. and (solder with (protect$4 with (storage or transportation)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/05 12:13